

9-16-03



102555994

IN. BOX ASSIGNMENTS

To the Honorable Commissioner of Patents
Please record the attached original document.

1. Name of conveying parties:

- 1) Shigeru KEMMOCHI
- 2) Mitsuhiro WATANABE
- 3) Hiroyuki TAI
- 4) Keisuke FUKAMACHI
- 5) Satoru YOKOUCHI



2. Name and address of receiving party:

Name: HITACHI METALS, LTD.

Additional name of conveying party attached? Yes No

Internal Address:

3. Nature of conveyance:

Street Address: 2-1, Shibaura 1-chome
Minato-ku, Tokyo, JAPAN

Assignment Merger

City:

Security Agreement Change of Name

State: Zip Code:

Other:

Additional name & Address attached?

Execution Date:

September 1, 2003

Yes No

4. Application number or patent number: If this document is being filed together with a new application, the execution date of the application:

A. Patent Application Number:

10/415,595

B. Patent Number:

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Mr. Ernest F. Chapman

6. Total number of applications and registrations involved:
1

7. Total fee (37 CFR 3.41): \$40

- Enclosed (Please charge deficiency to deposit account)
- Authorized to be charged to deposit account

Internal Address: FINNEGAN, HENDERSON, FARABOW, GARRETT & DUNNER, L.L.P.

Street Address: 1300 I Street, N.W.

City: Washington, D.C.

State: Zip: 20005-3315

8. Deposit Account No.: 06-0916

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

09/22/2003 010111 0000002A 10413595

01 FC:0021

40.00 DP

Ernest F. Chapman
Registration No. 25,961

Signature

September 16, 2003
Date

Total number of pages including cover sheet, attachments and documents: 3

SOLE/JOINT INVENTION
(U.S. Rights Only)**ASSIGNMENT**

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled:

HIGH-FREQUENCY SWITCH MODULE

for which I/WE executed an application for United States Letters Patent concurrently herewith or on _____ or filed an application for United States Letters Patent on April 30, 2003 (Serial No. 10/415,595); and

WHEREAS, **HITACHI METALS, LTD.**, a corporation of Japan, whose post office address is 2-1, Shibaura 1-chome, Minato-ku, Tokyo, Japan (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, my/our entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/We will, without further consideration, communicate with assignee, its successors and assigns, any facts known to me/us respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/we have empowered in the Declaration and Power of Attorney in this application, to insert here in parentheses (Application No. 10/415,595, filed April 30, 2003) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, I/We have hereunto set our hand(s).

Sole or First Assignor

Full Name	Signature	Date
Shigeru KEMMOCHI	<i>Shigeru Kemmochi</i>	Sep. 1, 2003
Address	Citizenship	
1-65, Beppu, Kumagaya-shi, Saitama-ken, Japan	Japan	

Second Assignor

Full Name	Signature	Date
Mitsuhiro WATANABE	<i>Mitsuhiro Watanabe</i>	Sep. 1, 2003
Address		Citizenship
1-65, Beppu, Kumagaya-shi, Saitama-ken, Japan		Japan

Third Assignor

Full Name	Signature	Date
Hiroyuki TAI	<i>Hiroyuki Tai</i>	Sep. 1, 2003
Address		Citizenship
73, Matoba 2-chome, Tottori-shi, Tottori-ken, Japan		Japan

Fourth Assignor

Full Name	Signature	Date
Keisuke FUKAMACHI	<i>Keisuke Fukamachi</i>	Sep. 1, 2003
Address		Citizenship
1-65, Beppu, Kumagaya-shi, Saitama-ken, Japan		Japan

Fifth Assignor

Full Name	Signature	Date
Satoru YOKOUCHI	<i>Satoru Yokouchi</i>	Sep. 1, 2003
Address		Citizenship
450-3, Nibori-Shinden, Kumagaya-shi, Saitama-ken, Japan		Japan